

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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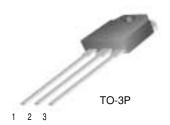
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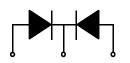
Features

- · Ultrafast with soft recovery
- · Low forward voltage

Applications

- Power switching circuits
- Output rectifiers
- Freewheeling diodes
- · Switching mode power supply





1. Anode 2. Cathode 3. Anode

ULTRA FAST RECOVERY POWER RECTIFIER

Absolute Maximum Ratings (per diode) T_C=25°C unless otherwise noted

| Symbol | Parameter | Value | Units |
|----------------------------------|---|--------------|-------|
| V _{RRM} | Peak Repetitive Reverse Voltage | 400 | V |
| I _{F(AV)} | Average Rectified Forward Current @ T _C = 100°C | 15 | Α |
| I _{FSM} | Non-repetitive Peak Surge Current 60Hz Single Half-Sine Wave | 150 | А |
| T _{J,} T _{STG} | Operating Junction and StorageTemperature | - 65 to +150 | °C |

Thermal Characteristics

| Symbol | Symbol Parameter | | Units |
|-----------------|--|-----|-------|
| $R_{\theta,JC}$ | Maximum Thermal Resistance, Junction to Case | 3.0 | °C/W |

Electrical Characteristics (per diode) T_C=25 °C unless otherwise noted

| Parameter | | Min. | Тур. | Max. | Units |
|---------------------------------------|--|---|---|---|--|
| Maximum Instantaneous Forward Voltage | | | | | V |
| I _F = 15A | T _C = 25 °C | - | - | 1.4 | |
| I _F = 15A | T _C = 100 °C | - | - | 1.3 | |
| Maximum Instantaneous Reverse Current | | | | | μΑ |
| @ rated V _R | $T_C = 25 ^{\circ}C$ | - | - | 40 | |
| ļ | T _C = 100 °C | - | - | 400 | |
| Maximum Reverse Recovery Time | | - | - | 50 | ns |
| Maximum Reverse Recovery Current | | - | - | 5.0 | Α |
| Maximum Reverse Recovery Charge | | - | - | 125 | nC |
| $(I_F = 15A, di/dt = 200A/\mu s)$ | | | | | |
| Avalanche Energy | | 1.0 | - | - | mJ |
| | $\label{eq:localization} \begin{aligned} &\text{Maximum Instantaneous Forward Voltage} \\ &\text{$I_F = 15$A} \\ &\text{$I_F = 15$A} \end{aligned}$ $\label{eq:localization} \\ &\text{Maximum Instantaneous Reverse Current} \\ &\text{@ rated V_R} \end{aligned}$ $\label{eq:localization} \\ &\text{Maximum Reverse Recovery Time} \\ &\text{Maximum Reverse Recovery Current} \\ &\text{Maximum Reverse Recovery Charge} \\ &\text{$(I_F = 15$A, di/dt = 200A/\mus)$} \end{aligned}$ | $\begin{tabular}{lllllllllllllllllllllllllllllllllll$ | $\begin{tabular}{lllllllllllllllllllllllllllllllllll$ | $\begin{array}{c ccccccccccccccccccccccccccccccccccc$ | $\begin{tabular}{l l l l l l l l l l l l l l l l l l l $ |

^{*} Pulse Test: Pulse Width=300μs, Duty Cycle=2%

Typical Characteristics

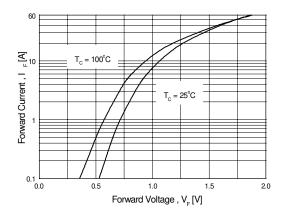


Figure 1. Typical Forward Voltage Drop vs. Forward Current

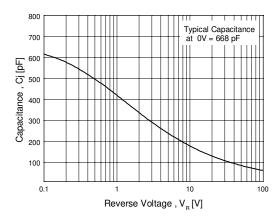


Figure 3. Typical Junction Capacitance

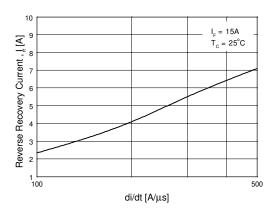


Figure 5. Typical Reverse Recovery Current vs. di/dt

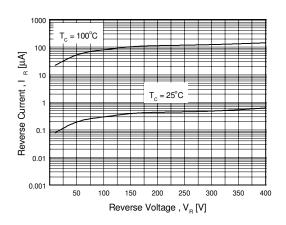


Figure 2. Typical Reverse Current vs. Reverse Voltage

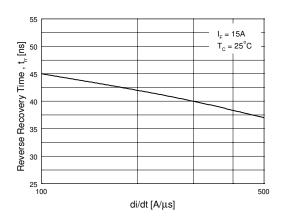


Figure 4. Typical Reverse Recovery Time vs. di/dt

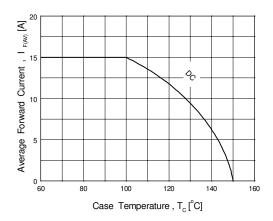
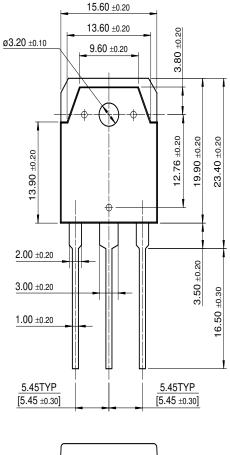
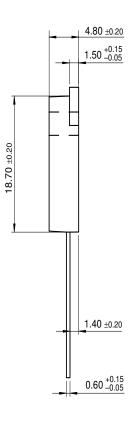


Figure 6. Forward Current Derating Curve

Package Dimensions

TO-3P





Dimensions in Millimeters

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| Datasheet Identification | Product Status | Definition |
|--------------------------|---------------------------|---|
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